

**High Power SPDT Switch**

**Description**

The CXG1077TN is a SPDT (Single Pole Dual Throw) antenna switch MMIC used in personal communication handsets such as JCDMA. This IC is designed using the Sony's GaAs J-FET process.

**Features**

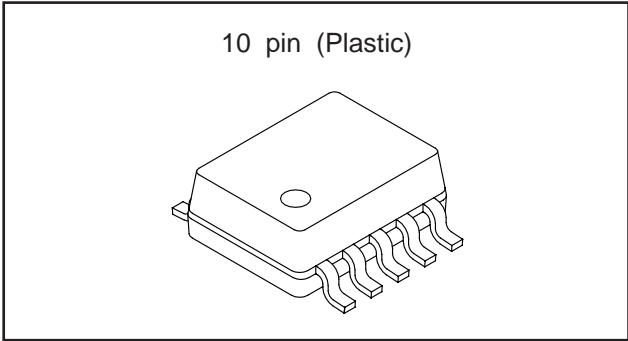
- Low control voltage     $V_{ctl} (H) = 2.8 V$
- Low control current     $I_{ctl} = 30 \mu A$  (Typ.) @2.8 V
- Low insertion loss    0.35 dB (Typ.) @900 MHz
- High power handling    P1dB: 33 dBm (Typ.) @900 MHz
- High intercept point     $I_{p3} = 60 dBm$  (Typ.)
- Small package        TSSOP-10pin

**Application**

SPDT switch for digital cellular telephones such as JCDMA handsets.

**Structure**

GaAs J-FET MMIC



**Absolute Maximum Ratings** (Ta=25 °C)

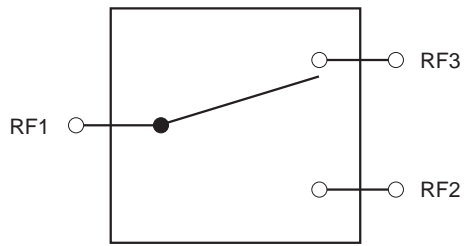
- Control voltage         $V_{ctl}$         7        V
- Operating temperature     $T_{opr}$     -35 to +85    °C
- Storage temperature     $T_{stg}$     -65 to +150   °C

**Operating Condition**

- Control voltage        CTL (H)    2.5 to 5        V
- CTL (L)    0 to 0.5        V

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Block Diagram



VCTLA	VCTLB	
High	Low	RF1-RF2 ON RF1-RF3 OFF
Low	High	RF1-RF2 OFF RF1-RF3 ON

Electrical Characteristics

(Ta=25 °C)

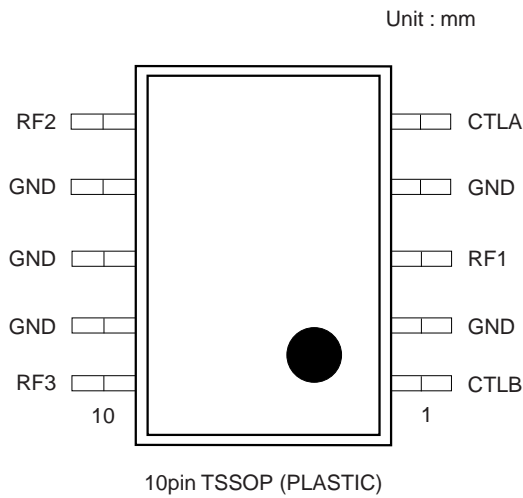
	Symbol	Condition	Min.	Typ.	Max.	Unit
Insertion loss	IL	*1		0.35	0.6	dB
		*2		0.5	0.8	dB
Isolation	ISO	*1	20	22		dB
		*2	15	17		dB
VSWR	VSWR	*1, *2		1.2	1.4	
Output harmonics	2fo, 3fo	*1			-30	dBm
		*2			-30	dBm
Input IP3	IIP3	*3		60	54	dBm
Input power for 1 dB compression	P1dB	*1	28	33		dBm
		*2	28	33		dBm
Switching speed TSW	TSW			100	300	ns
Control current	I CTL			30	50	μA

\*1 Pin=25 dBm, 900 MHz, CW, 0/2.8 V Control

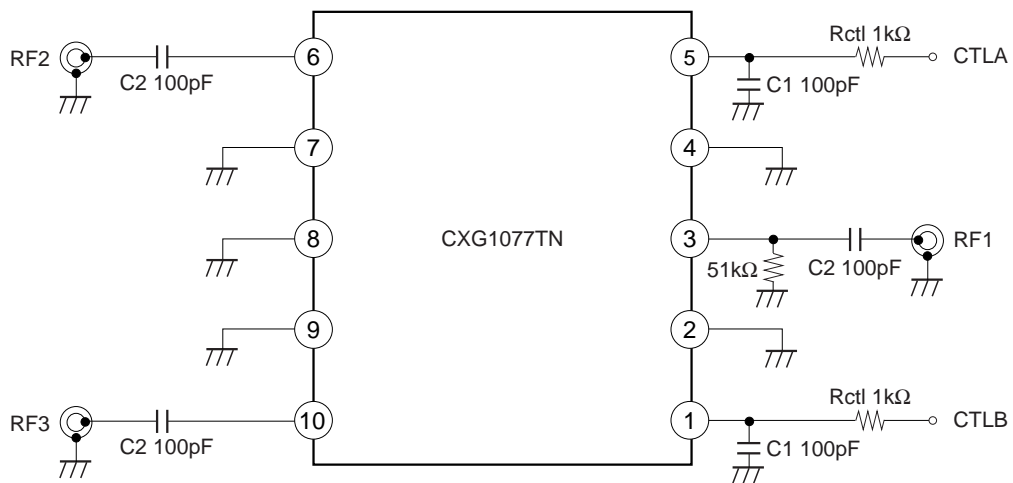
\*2 Pin=25 dBm, 1.8 GHz, CW, 0/2.8 V Control

\*3 Pin=21 dBm (900 MHz) +21 dBm (901 MHz), 0/2.8 V Control

Package Outline/Pin Configuration



Recommended Circuit

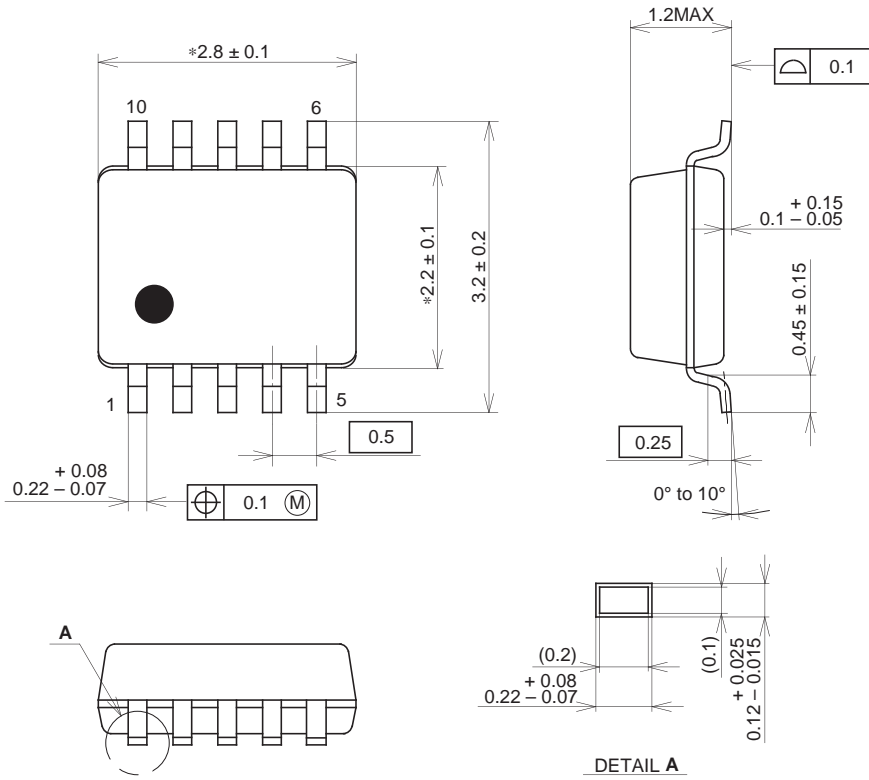


When using the CXG1077TN, the following external components should be used:

- C1: This is used for signal line filtering. 100 pF is recommended.
- C2: This is used for RF De-coupling and must be used in all applications. 100 pF is recommended.
- Rctl: This resistor is used to give improved ESD performance.

Package Outline Unit : mm

10PIN TSSOP(PLASTIC)



NOTE: Dimension "\*" does not include mold protrusion.

PACKAGE STRUCTURE

SONY CODE	TSSOP-10P-L01
EIAJ CODE	_____
JEDEC CODE	_____

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	COPPER ALLOY
PACKAGE MASS	0.02g